



## DOCUMENT CHANGE REQUEST

DCR number            847            Changes required for: General  
Date: 2014/10/13            Date sent: 2014/03/04  
Status: IMPLEMENTED

Originator: Alain Mouton  
Organisation: Astrium

Title:            Generic Specification for Microwave Monolithic Integrated Circuits

Number:            9010            Issue:            2

Other documents affected:

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Paragraph:

chart III(b)

Original wording:


Proposed wording:

As for ESCC 5000 (DCR 147) and ESCC 9000 (DCR 148), in chart III(b), a box "Hot Solder Dip (if applicable)" shall be added after "Electrical Measurements at Room Temperature" and before "Electrical Measurements at High and Low Temperatures".

A note (8) shall be added stipulating "For components with hot solder dip final lead finish, the hot solder dip processing shall be performed at any time prior to High and Low Temperatures Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC Basic Specification No. 23500.

Justification:

1. Coherence with ESCC 5000 (DCR 147) and ESCC 9000 (DCR 148).
2. Prevent any risk of loss of hermeticity following hot solder dip operations (refer to ESA alert EA-2003-EEE-07-A or GIDEP advisory).

Attachments:
N/A
Modifications:
N/A
Approval signature:

Date signed:
2014-10-13